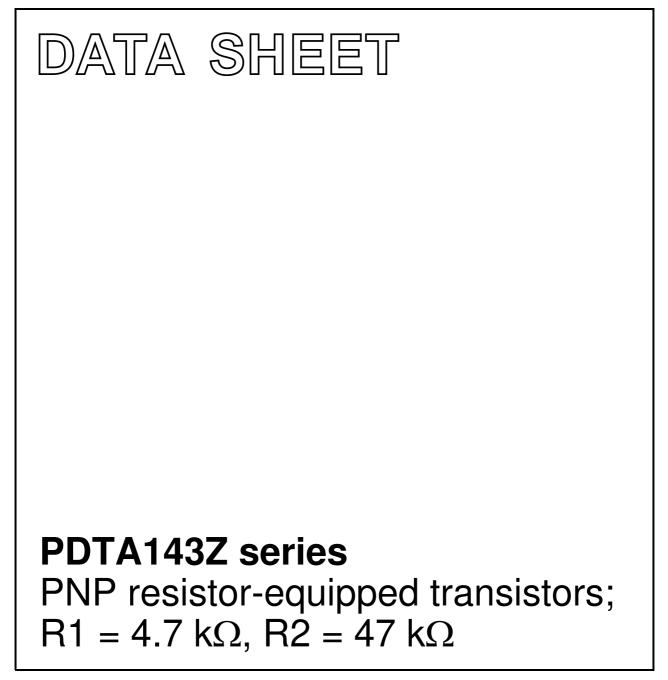
DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 2003 Sep 08 2004 Aug 05



PDTA143Z series

FEATURES

- · Built-in bias resistors
- Simplified circuit design
- Reduction of component count
- Reduced pick and place costs.

APPLICATIONS

- General purpose switching and amplification
- Inverter and interface circuits
- Circuit driver.

PRODUCT OVERVIEW

QUICK REFERENCE DATA

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
V _{CEO}	collector-emitter voltage	-	-50	V
lo	output current (DC)	-	-100	mA
R1	bias resistor	4.7	-	kΩ
R2	bias resistor	47	_	kΩ

DESCRIPTION

PNP resistor-equipped transistor (see "Simplified outline, symbol and pinning" for package details).

	PACKAGE				
TYPE NUMBER	PHILIPS	EIAJ	MARKING CODE	NPN COMPLEMENT	
PDTA143ZE	SOT416	SC-75	37	PDTC143ZE	
PDTA143ZEF	SOT490	SC-89	52	PDTC143ZEF	
PDTA143ZK	SOT346	SC-59	19	PDTC143ZK	
PDTA143ZM	SOT883	SC-101	DP	PDTC143ZM	
PDTA143ZS	SOT54 (TO-92)	SC-43	TA143Z	PDTC143ZS	
PDTA143ZT	SOT23	_	*19 ⁽¹⁾	PDTC143ZT	
PDTA143ZU	SOT323	SC-70	*47 ⁽¹⁾	PDTC143ZU	

Note

- 1. * = p: Made in Hong Kong.
 - * = t: Made in Malaysia.
 - * = W: Made in China.

PDTA143Z series

SIMPLIFIED OUTLINE, SYMBOL AND PINNING

	ER SIMPLIFIED OUTLINE AND SYMBOL		PINNING		
TYPE NUMBER			DESCRIPTION		
PDTA143ZS	Image: state sta	1 2 3	base collector emitter		
PDTA143ZE PDTA143ZEF PDTA143ZK PDTA143ZT PDTA143ZU	$\begin{array}{c} \hline 3 \\ \hline 1 \\ \hline \end{array} \\ \hline \end{array} \\ \hline \end{array} \\ \hline \end{array} \\ \hline \\ R2 \\ \hline \\ MDB271 \\ \hline \end{array} \\ \hline \end{array} \\ MDB271 \\ \hline \end{array}$	1 2 3	base emitter collector		
PDTA143ZM	2 1 Bottom view 3 1 R1 R1 R2 MDB267	1 2 3	base emitter collector		

PDTA143Z series

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	-50	V
V _{CEO}	collector-emitter voltage	open base	_	-50	V
V _{EBO}	emitter-base voltage	open collector	_	-10	V
VI	input voltage				
	positive		_	+5	V
	negative		_	-30	V
lo	output current (DC)		_	-100	mA
I _{CM}	peak collector current		_	-100	mA
P _{tot}	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$			
	SOT23	note 1	_	250	mW
	SOT54	note 1	_	500	mW
	SOT323	note 1	_	200	mW
	SOT346	note 1	_	250	mW
	SOT416	note 1	_	150	mW
	SOT490	notes 1 and 2	_	250	mW
	SOT883	notes 2 and 3	_	250	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Notes

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60 µm copper strip line.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	in free air		
	SOT23	note 1	500	K/W
	SOT54	note 1	250	K/W
	SOT323	note 1	625	K/W
	SOT346	note 1	500	K/W
	SOT416	note 1	833	K/W
	SOT490	notes 1 and 2	500	K/W
	SOT883	notes 2 and 3	500	K/W

Notes

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60 μ m copper strip line.

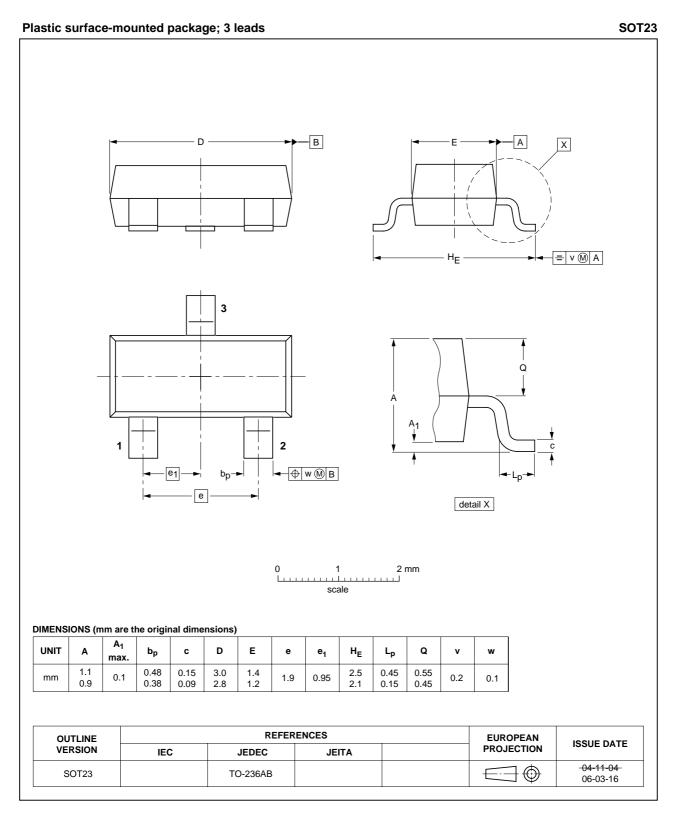
PDTA143Z series

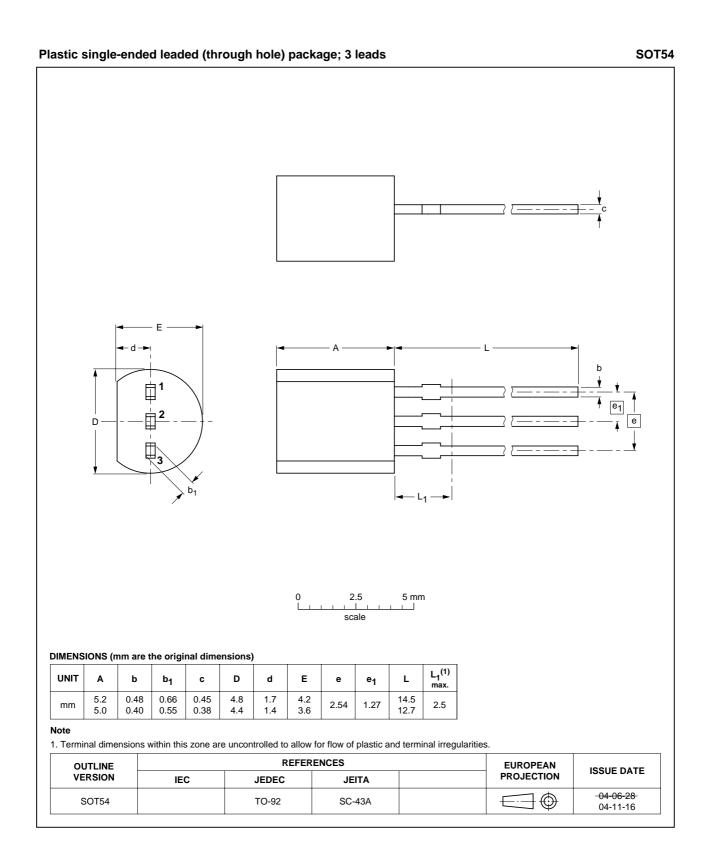
CHARACTERISTICS

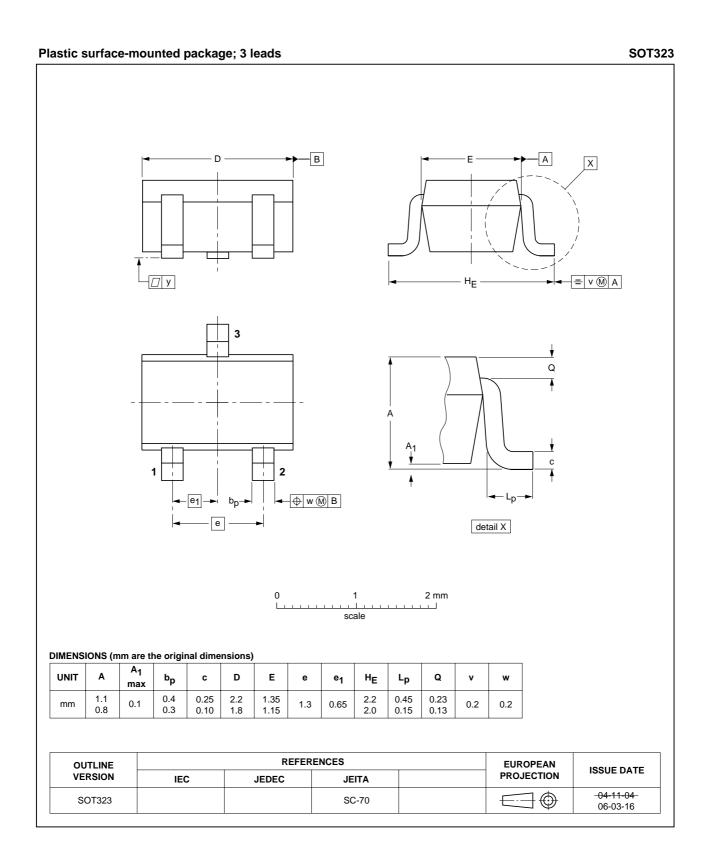
 T_{amb} = 25 °C unless otherwise specified.

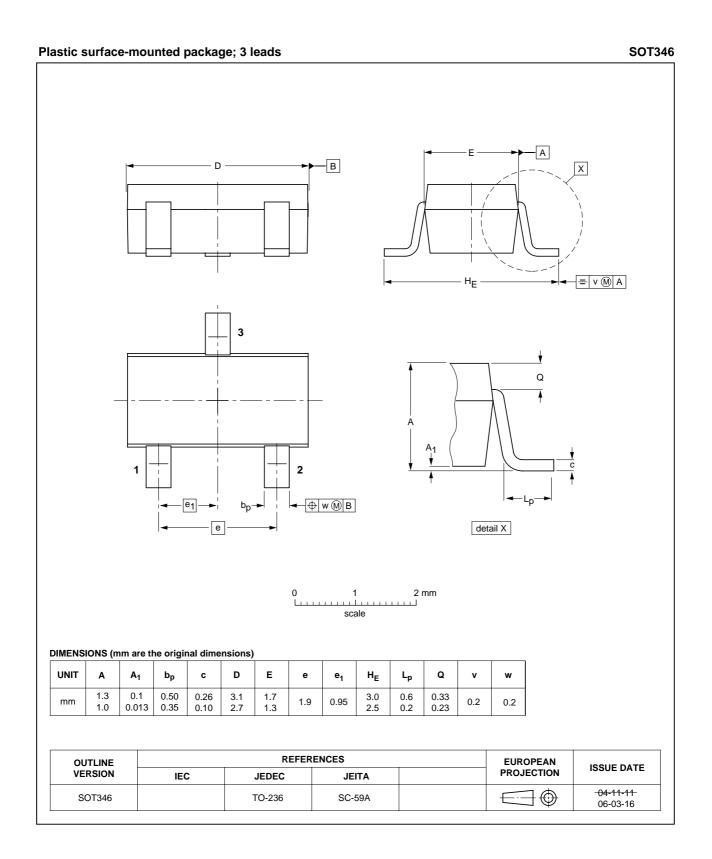
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	$V_{CB} = -50 \text{ V}; I_E = 0$	-	-	-100	nA
I _{CEO}	collector-emitter cut-off current	$V_{CE} = -30 \text{ V}; I_B = 0$	-	-	-1	μA
		$V_{CE} = -30 \text{ V}; I_B = 0; T_j = 150 ^{\circ}\text{C}$	-	-	-50	μA
I _{EBO}	emitter-base cut-off current	$V_{EB} = -5 \text{ V}; \text{ I}_{C} = 0$	-	-	-170	μA
h _{FE}	DC current gain	$V_{CE} = -5 \text{ V}; I_{C} = -10 \text{ mA}$	100	-	-	
V _{CEsat}	collector-emitter saturation voltage	$I_{C} = -5 \text{ mA}; I_{B} = -0.25 \text{ mA}$	-	-	-100	mV
V _{i(off)}	input-off voltage	$I_{C} = -100 \ \mu A; V_{CE} = -5 \ V$	-	-0.6	-0.5	V
V _{i(on)}	input-on voltage	$I_{C} = -5 \text{ mA}; V_{CE} = -0.3 \text{ V}$	-1.3	-0.9	-	V
R1	input resistor		3.3	4.7	6.1	kΩ
<u>R2</u> R1	resistor ratio		8	10	12	
C _c	collector capacitance	$I_E = i_e = 0; V_{CB} = -10 V; f = 1 MHz$	-	-	3	pF

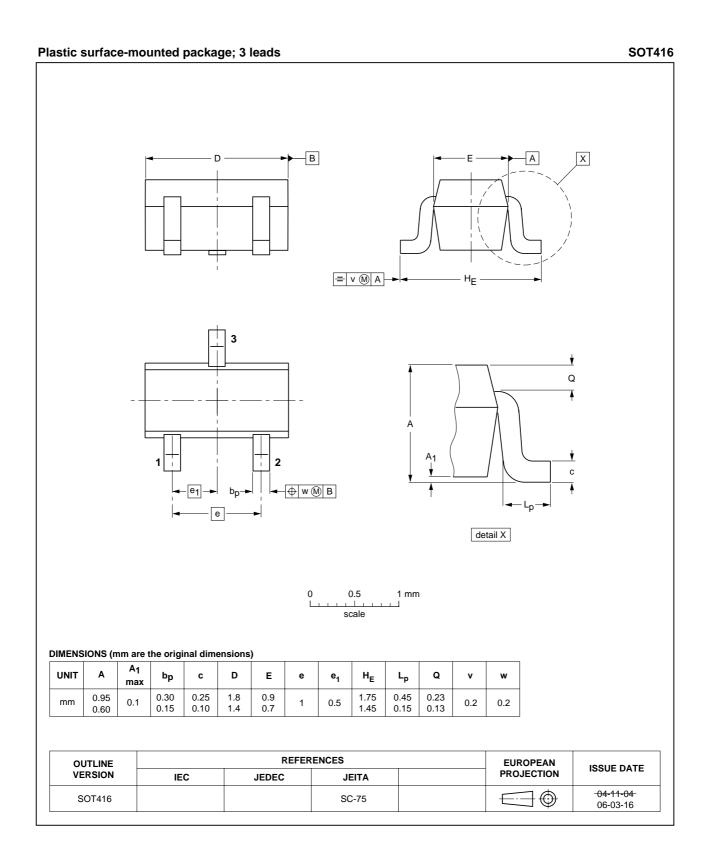
PACKAGE OUTLINES

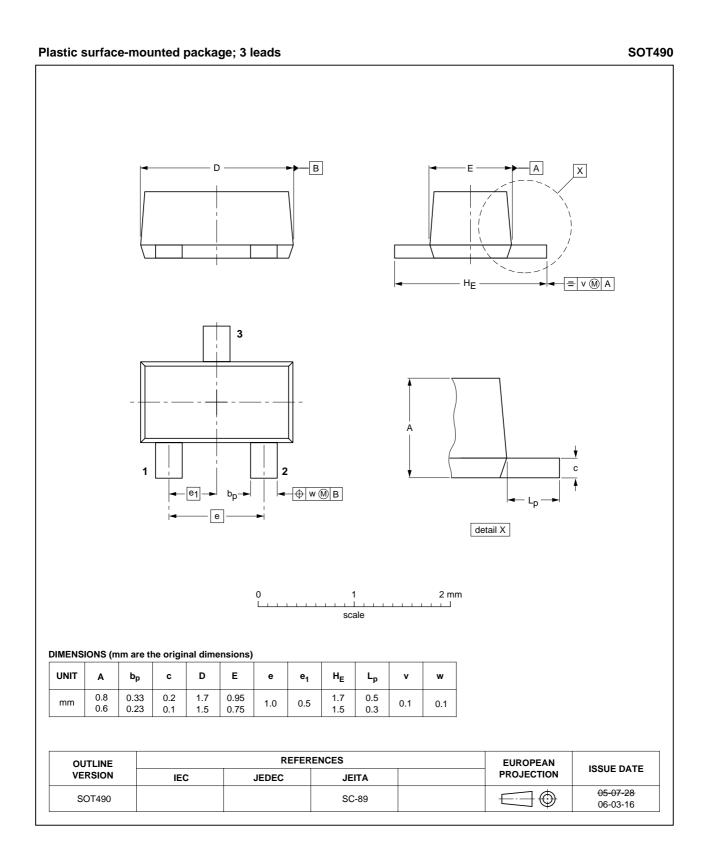


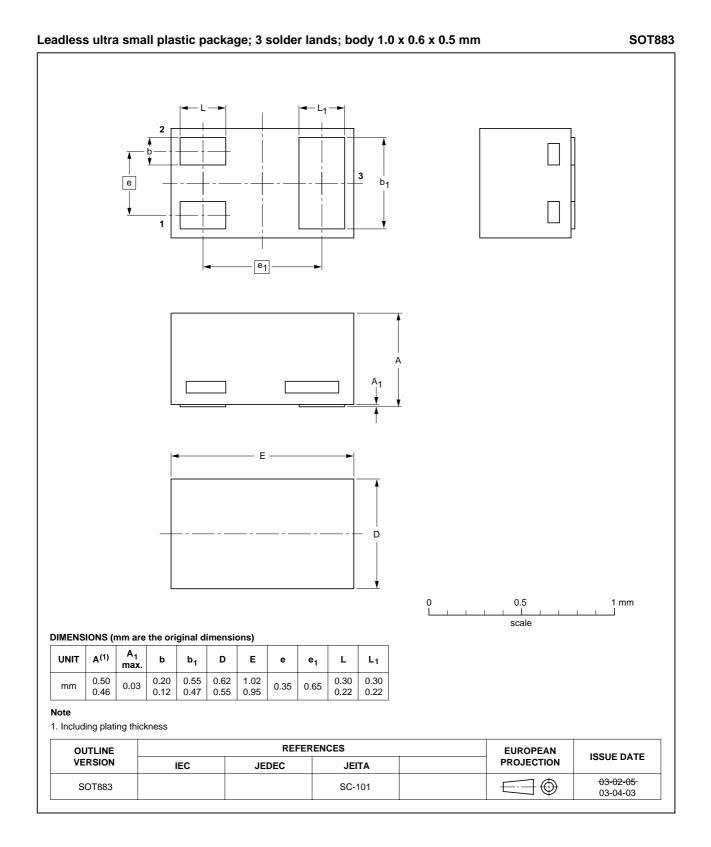












PDTA143Z series

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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